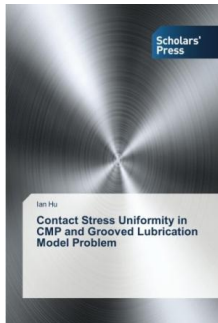


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CONTACT STRESS UNIFORMITY IN CMP AND GROOVED LUBRICATION MODEL PROBLEM



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